

Product/Process Change Notification

N° 2021-150-A2

Dear customer,

please find attached our Infineon Technologies AG PCN:

FINAL PCN: Change of parts of wafer production from Xintec Inc., Taiwan to Vanguard International Semiconductor Corporation, Taiwan and additional assembly site for D2Pak,Dpak,TO220 Mosfets.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-04-28.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492

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Products affected

Please refer to attached affected product list PCN_2021-150-A2_[customer-no].pdf

Detailed change information

Subject: FINAL PCN: Change of parts of wafer production from Xintec Inc., Taiwan to Vanguard International Semiconductor Corporation, Taiwan and additional assembly site for D2Pak,Dpak,TO220 Mosfets.

Reason/Motivation: The BEOL wafer production of the affected products will be transferred to location Vanguard International Semiconductor Corporation according to the global Infineon production strategy and Expansion of assembly production to assure continuity of supply and enable flexible manufacturing.

| Description | Old | New |
|---|--|---|
| PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip backside) | Back Grind/Back Metal: Grind A,Spin Etch | Back Grind/Back Metal: Grind B,Wet Etch Bench |
| PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site. | Xintec Inc., Taoyuan City, Taiwan | Vanguard International Semiconductor Corporation, Hsinchu, Taiwan |
| PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal) | D2pak, Dpak,TO220 only: Ni plated in all area Cu on die pad | D2pak, Dpak,TO220 only and TFME: Only Bare Cu in all area except T-post with Ni plate |
| PROCESS - ASSEMBLY: Change of mold compound / encapsulation material | TO220 only: MG15F-35A | TO220 only: KE-G300BH |
| PROCESS - ASSEMBLY: Change of product marking | D2pak, Dpak,TO220 only: No Site code | D2pak, Dpak,TO220 only: TFME affected only: Site Code M |
| PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site. | D2pak, Dpak,TO220 only: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico | D2pak, Dpak,TO220 only: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd(TFME) |

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| | | |
|--|--|---|
| TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site. | D2pak, Dpak, TO220 only: Final Test Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico | D2pak, Dpak, TO220 only: Final Test , Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd(TFME) |
|--|--|---|

Product identification

traceability is ensured via lot code

Anticipated impact of change

Based on the qualification performed, Infineon does not expect any impact on quality, function and reliability.
Please refer to QTR

DeQuMa-ID(s): SEM-PW-06 / SEM-PW-13 / SEM-PA-04 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-TF-01

Attachments

| | |
|-----------------------------------|-----------------------|
| PCN_2021-150-A2_[customer-no].pdf | affected product list |
| 2_cip21150_A2 | qualification report |

Time schedule

| | |
|--------------------------------|------------|
| Final qualification report | 2022-03-15 |
| First samples available | 2022-03-15 |
| Intended start of delivery [1] | 2022-09-15 |

[1] Provided date or earlier after customer approval

If you have any questions, please do not hesitate to contact your local sales office.

PCN 2021-150-A2

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Affected products sold to DIGI-KEY (4002348)

| Sales name | SP number | OPN | Package | Customer part number |
|----------------|-------------|----------------|----------------|----------------------|
| AUIRF1324WL | SP001516588 | AUIRF1324WL | PG-TO262-3-903 | AUIRF1324WL |
| AUIRF1404Z | SP001520218 | AUIRF1404Z | PG-TO220-3-904 | AUIRF1404Z |
| AUIRF3205Z | SP001518518 | AUIRF3205Z | PG-TO220-3-904 | AUIRF3205Z |
| AUIRF540Z | SP001516500 | AUIRF540Z | PG-TO220-3-904 | AUIRF540Z |
| AUIRFP4568 | SP001519624 | AUIRFP4568 | PG-TO247-3-901 | AUIRFP4568 |
| AUIFR3806TRL | SP001521230 | AUIFR3806TRL | PG-TO252-3-901 | AUIFR3806TRL |
| AUIFR4620TRL | SP001516660 | AUIFR4620TRL | PG-TO252-3-901 | AUIFR4620TRL |
| AUIRFS3107TRL | SP001521708 | AUIRFS3107TRL | PG-TO263-3-901 | AUIRFS3107TRL |
| AUIRFS4310ZTRL | SP001516740 | AUIRFS4310ZTRL | PG-TO263-3-901 | AUIRFS4310ZTRL |